

an exhaust line to exhaust pressurizing gas from the processing chamber;  
a pressure regulator to regulate pressure within the processing chamber;  
a source of electroless plating solution;  
a sprayer provided within the processing chamber and connected to the  
source of electroless plating solution to spray the electroless plating solution onto the  
at least one substrate; and  
a drain provided in the processing chamber to drain the electroless plating  
solution from the processing chamber.

Please add the following new claims to the application:

28. The apparatus according to claim 1, further comprising a source of inert gas,  
wherein the pressurizing gas comprises the inert gas and the inlet to provide  
pressurizing gas is connected to the source of inert gas.

29. The apparatus according to claim 14, wherein the means for pressurizing the  
processing chamber includes means for introducing inert gas into the processing  
chamber.